9500W Semi Automatic BGA Rework Station with 5 Thermocouple Ports and AC380V Power Supply for PCB Rework

Our Product Introduction

Basic Information

- Brand Name: Wisdomshow
- Certification: CE
- Model Number: WDS-900
- Minimum Order Quantity: 1
- Packaging Details: Wooden Case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200Sets / Month



Product Specification

- Applicable Chip Size: 0.8×0.8mm-80×80mm
- Temperature Control: Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
- Placement Accuracy: ±0.02mm
- Total Power: 9500W
- Power Supply: AC380V±10%, 50/60Hz
- Thermocouple Ports: 5 Pcs
- Max PCB Size: 760×630mm
- Highlight: **9500W Semi Automatic BGA Rework Station**, **BGA Rework Station with 5 Thermocouple Ports** , **AC380V BGA Rework Station for PCB Rework**

for more products please visit us on bgaxraymachine.com

for more products please visit us on bgaxraymachine.com

Product Description

Product Description:

The Semi Automatic BGA Rework Station is a high-performance and versatile tool designed for precision cpu repair and advanced electronic component reworking. With a robust total power of 9500W, this station delivers exceptional heating capabilities, ensuring efficient and reliable operation for a wide range of applications. Whether you are working on delicate chips or larger circuit boards, this BGA rework station is engineered to meet the demanding requirements of modern electronics repair and manufacturing environments.
One of the standout features of this BGA rework station is its compatibility with a broad spectrum of chip sizes. It supports chips ranging from as small as 0.8×0.8mm to as large as 80×80mm, making it ideal for various cpu repair tasks and other semiconductor component soldering and desoldering processes. This wide applicability allows technicians and engineers to handle everything from miniature processors to sizable integrated circuits with confidence and precision.
The station accommodates a maximum PCB size of 760×630mm, providing ample workspace for working on large circuit boards without compromising stability or control. This generous capacity ensures that complex assemblies and multi-chip modules can be serviced efficiently, reducing the need for constant repositioning and minimizing the risk of damage to sensitive components.
Precision temperature control is critical in any BGA rework process, and this station excels in that regard. It features five thermocouple ports, enabling accurate temperature monitoring at multiple points on the PCB and components. The closed-loop K-type thermocouple system ensures real-time feedback and precise regulation of temperature, maintaining optimal conditions throughout the rework process. This technology helps prevent overheating and thermal damage, which are common concerns during cpu repair and other delicate operations.
Additionally, the station offers independent heating control for both the upper and lower heating elements. This dual-zone heating capability allows users to fine-tune the thermal profile for different stages of the rework process, optimizing heat distribution and improving solder joint quality. The temperature accuracy is maintained within ±1°C, providing exceptional consistency and repeatability. This high level of control is especially important when working with advanced BGA packages and sensitive electronic components.
The integration of hot air heating further enhances the versatility of this BGA rework station. Hot air heating is a preferred method in many rework scenarios because it provides uniform heat distribution without direct contact, reducing the risk of mechanical damage. This method is particularly effective for removing and reflowing components on densely populated PCBs and complex assemblies. The station's hot air system is designed to deliver stable and adjustable airflow, ensuring optimal heating performance for various component sizes and types.
In summary, the Semi Automatic BGA Rework Station combines powerful heating capabilities, extensive compatibility with chip and PCB sizes, and advanced temperature control technologies to provide a reliable solution for cpu repair and electronic component rework. Its user-friendly design, coupled with precise hot air heating and independent upper and lower heating zones, makes it an indispensable tool for technicians and engineers seeking quality, efficiency, and safety in BGA rework operations.

Features:

Product Name: Semi Automatic BGA Rework Station
Thermocouple Ports: 5 Pcs for precise temperature monitoring
Applicable Chip Size: Supports chips from 0.8×0.8mm to 80×80mm
Temperature Control: Closed-loop K-type Thermocouple with upper & lower independent heating and ±1°C accuracy
Max PCB Size: Accommodates PCBs up to 760×630mm
Placement Accuracy: High precision placement with ±0.02mm accuracy
Equipped with an advanced optical alignment system for accurate component positioning
Ideal for efficient and reliable motherboard repair
Designed to enhance productivity in motherboard repair tasks

Technical Parameters:

Total Power	9500W
Applicable Chip Size	0.8×0.8mm - 80×80mm
Temperature Control	Closed-loop K-type Thermocouple, Upper & Lower Independent Heating, ±1°C Accuracy
Max PCB Size	760×630mm
Thermocouple Ports	5 Pcs
Placement Accuracy	±0.02mm
Power Supply	AC380V±10%, 50/60Hz

Applications:

The Wisdomshow WDS-900 Semi Automatic BGA Rework Station is an advanced and reliable solution designed for precise and efficient soldering and desoldering of BGA chips. Originating from Shenzhen, China, this CE-certified device is ideal for various professional applications in electronics manufacturing, repair, and prototyping. Its infrared preheating table ensures uniform and controlled heating, reducing thermal stress and improving the quality of the rework process. With a total power of 9500W and five thermocouple ports, the WDS-900 offers exceptional temperature control and monitoring capabilities, making it suitable for handling sensitive and complex BGA components.
The WDS-900 model is perfectly suited for scenarios involving the repair or replacement of BGA chips ranging in size from 0.8×0.8mm up to 80×80mm. This wide applicability makes it an indispensable tool in industries such as telecommunications, consumer electronics,

automotive electronics, and computer hardware manufacturing. Its semi automatic operation enhances productivity and accuracy, allowing technicians to achieve placement accuracy within ±0.02mm, thereby minimizing errors and improving the success rate of rework tasks.

In terms of practical application occasions, this BGA rework station is extensively used in quality control labs, R&D facilities, and repair centers, where precision and repeatability are critical. The infrared preheating table allows for gentle and even heating of printed circuit boards (PCBs), preventing warping or damage during the reflow process. Additionally, the power supply requirements of AC380V±10% at 50/60Hz ensure stable and consistent performance in demanding production environments.

The product is thoughtfully packaged in a sturdy wooden case, providing safe transportation and easy storage. With a supply ability of 200 sets per month and a delivery time of just 3-5 days, the Wisdomshow WDS-900 is readily available to meet urgent production needs. Its minimum order quantity of one set and payment terms via TT make it accessible for both small workshops and large-scale manufacturers.

Overall, the Wisdomshow WDS-900 Semi Automatic BGA Rework Station with its infrared preheating table is an essential tool for anyone involved in electronics assembly and repair. Its combination of high power, precise temperature control, and semi automatic functionality ensures high-quality rework results, making it a trusted choice for various professional scenarios worldwide.

Shenzhen Wisdomshow Technology Co.,ltd

+86 18926538696 elysia.li@wdsbga.cn bgaxraymachine.com

No. 3 Kangtai 3rd Road, Shatou Community, Shajing Street, Bao'an District, Shenzhen, China